

ZPMV2.E248803 - Wiring, Printed - Component

Wiring, Printed - Component

See General Information for Wiring, Printed - Component

SHING TECH ELECTRONICS CO LTD

303 SEC 2 NANSHAN RD

LUZHU TOWNSHIP

TAOYUAN HSIEN, 338 TAIWAN



E248803

Type	Cond Width		Cond Thk mic(mil)	SS/ DS/ DSO	Max	Solder		Max	Flame Class	Meets UL796 DSR	C T I
	Min mm(in)	Min Edge mm(in)			Area Diam mm(in)	Limits C	Oper Temp C				
Multilayer metal base printed wiring boards.											
AL02	0.1 (0.004)	0.2 (0.008)	34 (1.34) Int:68	SS	50.8 (2.0)	260	10	140	V-0	All	1
Multilayer printed wiring boards.											
AM01	1.6 (0.063)	4.8 (0.189)	17 (0.67)	DS	25.4 (1.0)	260	10	130	V-0	All	-
BM01	0.075 (0.003)	0.10 (0.004)	17 (0.67) Int:68	DS	25.4 (1.0)	260	10	105	V-0	All	-
BM02	0.12 (0.005)	0.12 (0.005)	17 (0.67) Int:27	DS	25.4 (1.0)	260	10	130	V-0	All	-
GM01	0.10 (0.004)	0.10 (0.004)	12 (0.47) Int:102	DS	25.4 (1.0)	260	10	130	V-0	All	2
GM01A	0.075 (0.003)	0.075 (0.003)	12 (0.47) Int:102	DS	25.4 (1.0)	260	10	130	V-0	All	4
HM01(a)	0.10 (0.004)	0.10 (0.004)	12 (0.47) Int:210	DS	50.8 (2.0)	260	10	130	V-0	All	3
RM01	0.075 (0.003)	0.075 (0.003)	17 (0.67) Int:102	DS	50.8 (2.0)	260	10	130	V-0	All	*
Single layer metal base printed wiring boards.											

AL01	0.1 (0.004)	0.2 (0.008)	34 (1.34)	SS	50.8 (2.0)	260	10	140	V-0	All	0
AL01A	0.1 (0.004)	0.1 (0.004)	17 (0.67)	SS	50.8 (2.0)	260	10	130	V-0	All	0
AL03	0.10 (0.004)	0.10 (0.004)	17 (0.67)	DS	50.8 (2.0)	260	10	130	V-0	-	0
Single layer printed wiring boards.											
AD01	1.6 (0.063)	4.8 (0.189)	17 (0.67)	DS	25.4 (1.0)	260	10	130	V-0	All	-
BD01	0.075 (0.003)	0.1 (0.004)	17 (0.67)	DS	25.4 (1.0)	260	10	105	V-0	All	-
BD02	0.12 (0.005)	0.12 (0.005)	17 (0.67)	DS	25.4 (1.0)	260	10	130	V-0	All	-
GD01	0.10 (0.004)	0.10 (0.004)	12 (0.47)	DS	25.4 (1.0)	260	10	130	V-0	All	2
GD01A	0.075 (0.003)	0.075 (0.003)	12 (0.47)	DS	25.4 (1.0)	260	10	130	V-0	All	4
HD01(a)	0.10 (0.004)	0.10 (0.004)	12 (0.47)	DS	50.8 (2.0)	260	10	130	V-0	All	3
RD01	0.075 (0.003)	0.075 (0.003)	17 (0.67)	DS	50.8 (2.0)	260	10	130	V-0	All	0

(a) - For Types HD01 & HM01: Min. Cond. Width = 0.10 mm/ Edge Cond. Width = 0.10 mm for External Cu Thk = 12 ~ 102 mic; Min. Cond. Width = 0.40 mm/ Edge Cond. Width = 0.40 mm for External Cu Thk = 102 ~ 210 mic.

* - CTI marking is optional and may be marked on the printed wiring board.

Marking: Company name or trademark   or file number and type designation. May be followed by a suffix to denote factory identification or burning test classification.

Last Updated on 2020-02-19

在此資料庫中出現的公司名稱或產品，並不代表其產品本身的製造有經過UL 後續檢驗服務的把關。僅有附 UL 標誌的產品才可被視為取得認證，並涵蓋在UL 後續檢驗服務範圍裡。請務必確認產品上是否有此標誌。

UL 允許複製線上認證目錄中所包含的資料，但必須符合以下條件：1.指南資訊、零組件、構造、設計、系統和/或認證(檔案) 必須以完整的方式呈現，且不得誤導、不得操弄這些資料(或圖繪)。2.「經 UL 許可自線上認證目錄轉載」的聲明，必須顯示在擷取的資料旁。此外，轉載的資料必須包含以下格式的版權聲明：“© 2020 UL LLC”